### **Brock J. LaMeres**

### **Agilent Technologies**

"RF Effects in PCB Design"

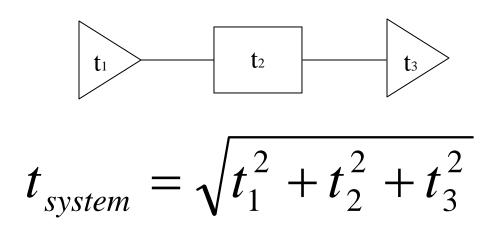
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### **Topics:**

- 1) Printed Circuit Board Via
- 2) Bandwidth Estimation
- 3) Effect of Via on Bandwidth

# PCB Bandwidth Estimation (Background)

- The overall risetime of a system is the RMS average of all risetimes in the system:



### Risetime to Bandwidth Conversion (Risetime BW Product)

$$t_{RISE} * BW = 0.35$$

# PCB Bandwidth Estimation (Background)

- The MAXIMUM Toggle rate of a digital system is:

$$f_{\text{max}} = \frac{0.35}{t_{RISE}}$$

#### **Time Constant to Risetime Conversion**

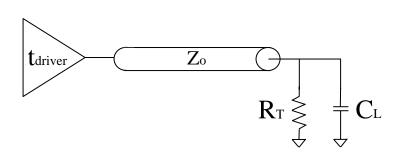
$$t_{RISE} = 2.2 * Tau$$

$$(Tau = RC \text{ or } ZC)$$

## PCB Bandwidth Estimation (Series vs. Parallel Termination)

#### Parallel Termination Example

$$t_{driver} = 400 \text{ ps}$$
  
 $Z_{o} = RL = 50 \Omega$   
 $CL = 6 \text{ pF}$ 

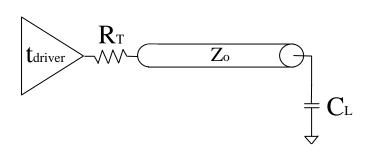


$$Tau(load) = (50//50)*6p = 150 \text{ ps}$$
  
 $trise(load) = 2.2*(150p) = 330 \text{ ps}$   
 $t_{system} = \sqrt{(400p)^2 + (330p)^2} = 519 \text{ ps}$   
 $f_{max} = \frac{0.35}{519p} = 674 \text{ MHz}$ 

## PCB Bandwidth Estimation (Series vs. Parallel Termination)

#### Series Termination Example

$$t_{driver} = 400 \text{ ps}$$
  
 $Z_{o} = RL = 50 \Omega$   
 $CL = 6 \text{ pF}$ 



$$Tau(load) = (50)*6p$$
 = 300 ps  
trise(load) = 2.2\*(300p) = 660 ps  
 $t_{system} = \sqrt{(400p)^2 + (660p)^2}$  = 772 ps  
 $f_{max} = \frac{0.35}{772p}$  = 454 MHz

### **PCB Bandwidth Estimation**

#### (Series vs. Parallel Termination)

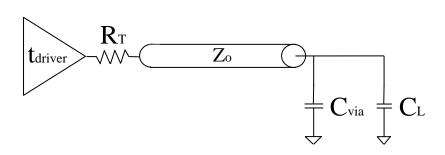
#### Addition of a Via

$$tdriver = 400 ps$$

$$Zo=RL=50 \Omega$$

$$CL=6 pF$$

$$Cvia = 1pF$$



$$Tau(load) = (50)*6p$$
 = 300 ps  
trise(load) = 2.2\*(300p) = 660 ps

$$Tau(via) = (50)*1p$$
 = 50 ps  
trise(via) = 2.2\*(50p) = 110 ps

$$t_{system} = \sqrt{(400p)^2 + (660p)^2 + (110p)^2} = 780 \text{ ps}$$

$$f_{\text{max}} = \frac{0.35}{780p} = 448 \text{ MHz}$$

#### - a loss of 7MHz due to the via

# PCB Bandwidth Estimation (Compensation)

- 1) An inductor can be used in series w/ a capacitive load to raise the load impedance.
- 2) The ground plane clearance can be backed off around a via to make it look less capacitive.

### "RF Effects in PCB Design"

**Comments or Question?**